INVESTIGATION OF ADHESION BETWEEN MICROWAVE PLASMA TREATED EPOXY AND SILICONE

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UNIVERSITI SAINS MALAYSIA 2020

INVESTIGATION OF ADHESION BETWEEN MICROWAVE PLASMA TREATED EPOXY AND SILICONE

by

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Thesis submitted in fulfilment of the requirements for the degree of Doctor of Philosophy

ACKNOWLEDGEMENT

I would like to express my sincere gratitude to my supervisor Professor Ir. Dr. Cheong Kuan Yew for his constant guidance, help and support for the project. His dedication and enthusiasm in research have greatly inspired his students.

I am very grateful to Collaborative Research in Engineering, Science & Technology (CREST) for providing the funding of this research. My deep appreciation goes to Dr. NorAzmi Bin Alias, Puan Tazura Binti Hazilla and Ms. Lim Poi Hong for providing insight and expertise that greatly assisted the project.

My sincere thank goes to my industrial leader Encik Ahmad Faiz Roslan, Dr. David Lacey and Mr. Lim Choon Kim from Osram Opto Semiconductors (Malaysia) for their guidance and advice. I would like to express my appreciation to the Osram Design Team and Reliability Team for their great support and help.

A special thank goes to Professor Dr. Khairulnisak Binti Abdul Razak for giving me guidance and help. I am grateful to Dr. Sivakumar A/L Ramakrishnan for providing me the statistical knowledge and skills. A special thank goes to Encik Mohd. Azam Bin Rejab and Encik Mohammad Azrul Bin Zainol Abidin for their continuous support and assistance. My special appreciation goes to my colleagues and friends Dr. Banu Poobalan, Dr. Lim Zhe Xi, Ms. Myo Myo Thu, Puan Norasiah Binti Mohammad Noordin, Mr. Tran Thanh Tam, Dr. Teo Pao Ter, Dr. Kho Chun Min, Dr. Nyein Nyein, Dr. Mustaffa Ali Azhar Taib, Cik Nurain Najihah Alias and Puan Ervina Junaidi for their advice and support.

Last but not least, I would like to acknowledge with heartfelt gratitude, the encouragement, love and moral support from my mother, siblings and friends, throughout this challenging experience.

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